

HM8840Q Dual N-Channel Enhancement-Mode MOSFET

General Description

Thigh Density Cell Design For Ultra Low On-Resistance Fully Characterized Avalanche Voltage and Current Improved Shoot-Through FOM

- Simple Drive Requirement
- Small Package Outline
- Surface Mount Device

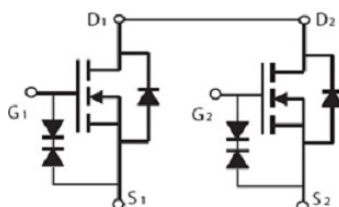
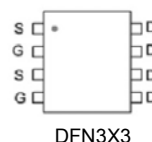
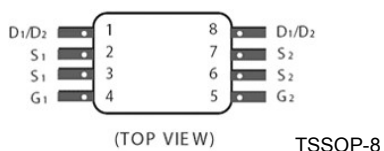
Features

For a single MOSFET

- $V_{DS} = 20V$
- $R_{DS(ON)} = 8.5m\Omega @ V_{GS}=4.5V$

Pin configurations

See Diagram below



Absolute Maximum Ratings

Parameter		Symbol	Rating	Units
Drain-Source Voltage		V_{DS}	20	V
Gate-Source Voltage		V_{GS}	± 12	V
Drain Current	Continuous	I_D	10	A
	Pulsed		85	
Total Power Dissipation	@TA=25°C	P_D	1.7	W
Operating Junction Temperature Range		T_J	-55 to 150	°C

Electrical Characteristics (T _J =25℃ unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS (Note 2)						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0 V	20			V
I _{DSS}	Drain to Source Leakage Current	V _{DS} = 16V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =10V			10	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =250μA	0.3	0.65	1	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V, I _D =10A		8.5	9.5	mΩ
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V, f=1MHz	1000	1255	1510	pF
C _{oss}	Output Capacitance		150	220	290	pF
C _{rss}	Reverse Transfer Capacitance		100	168	235	pF
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =10V, I _D =10A	10	12.5	15	nC
Q _{gs}	Gate Source Charge			5.5		nC
Q _{gd}	Gate Drain Charge			6.5		nC
t _{d(on)}	Turn-On Delay Time	V _{GEN} =4.5V, V _{DD} =10V, R _{GEN} =3Ω		1.1		ns
t _{d(off)}	Turn-Off Delay Time			7		ns
t _{d(r)}	Turn-On Rise Time			2.6		ns
t _{d(f)}	Turn-Off Fall Time			7.4		ns
Thermal Resistance						
Symbol	Parameter		Typ	Max		Units
R _{θJC}	Thermal Resistance Junction to Case(t≤10s)		30	40		℃/W

Typical Characteristics

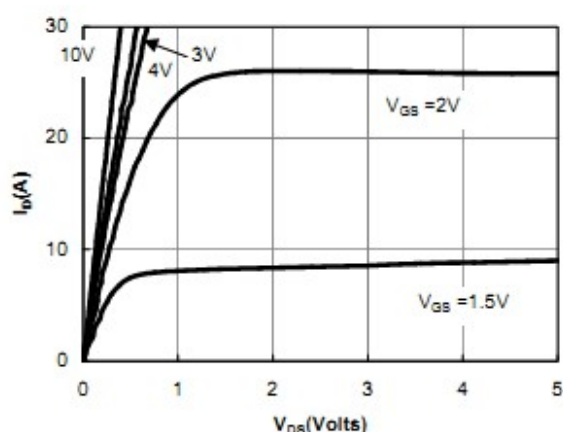


Figure 1: On-Regions Characteristics

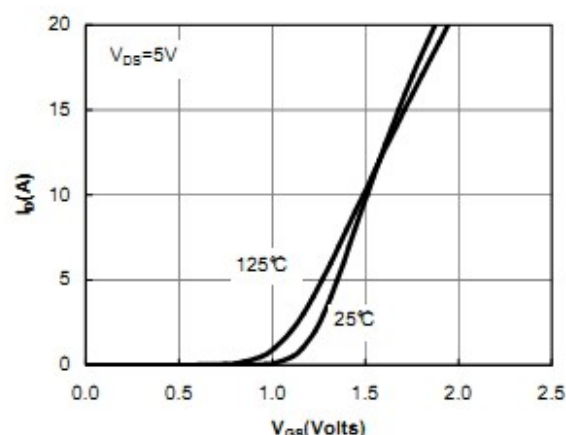


Figure 2: Transfer Characteristics

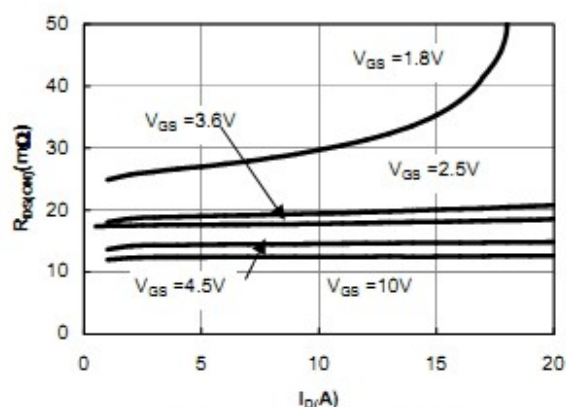


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

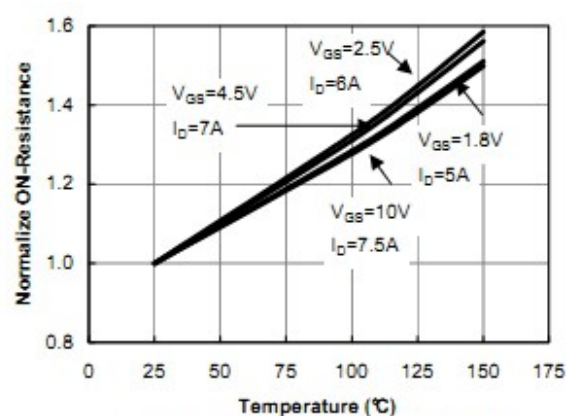


Figure 4: On-Resistance vs. Junction Temperature

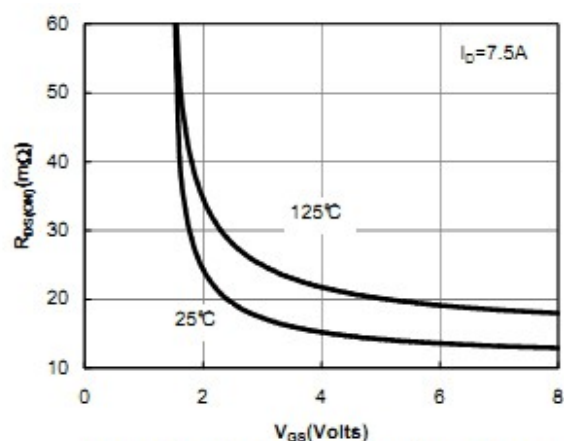


Figure 5: On-Resistance vs. Gate-Source Voltage

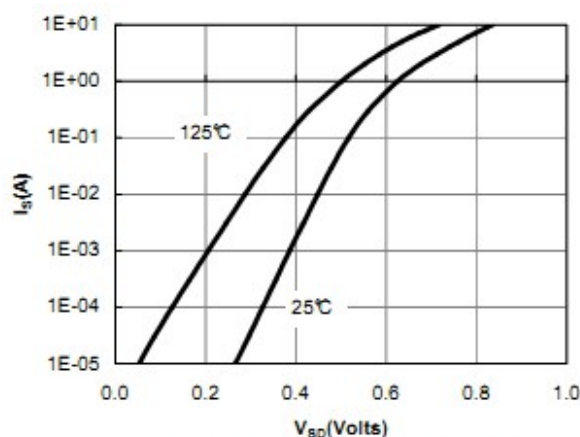


Figure 6: Body-Diode Characteristics

Typical Characteristics

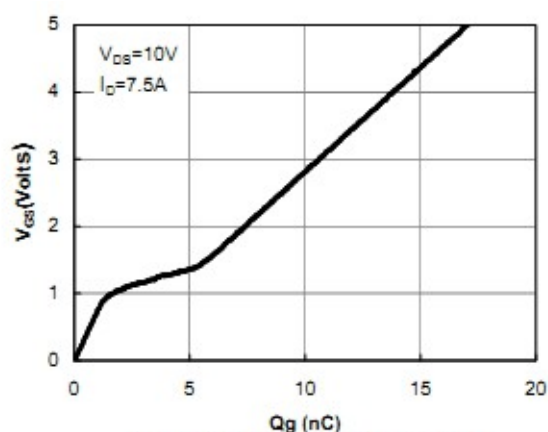


Figure 7: Gate-Charge Characteristics

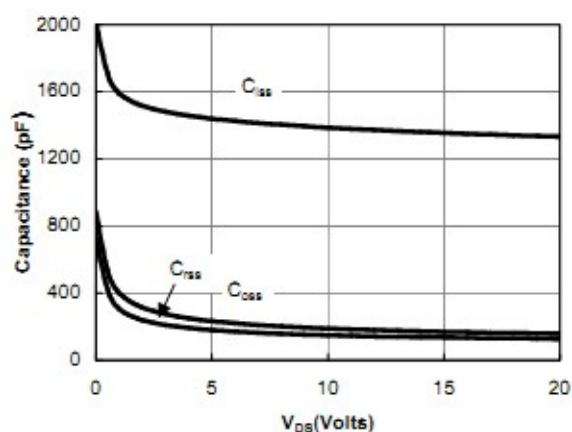


Figure 8: Capacitance Characteristics

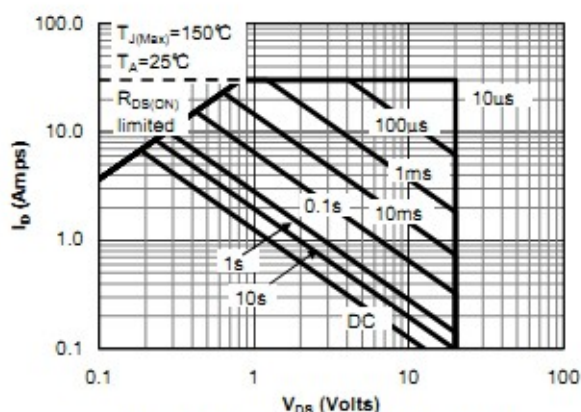


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

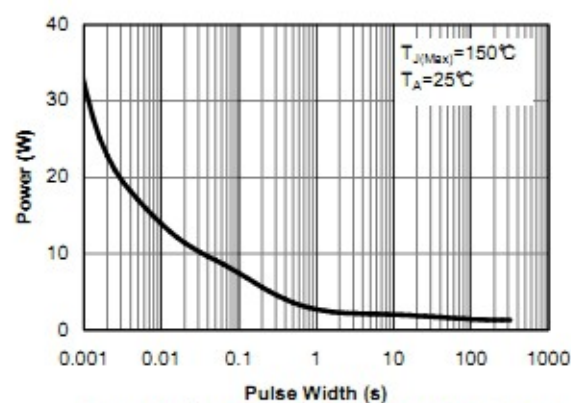


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

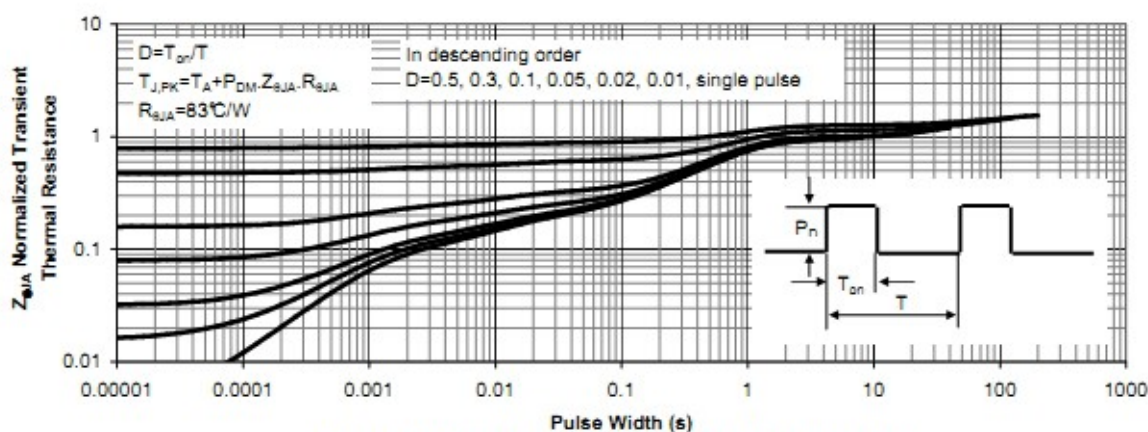
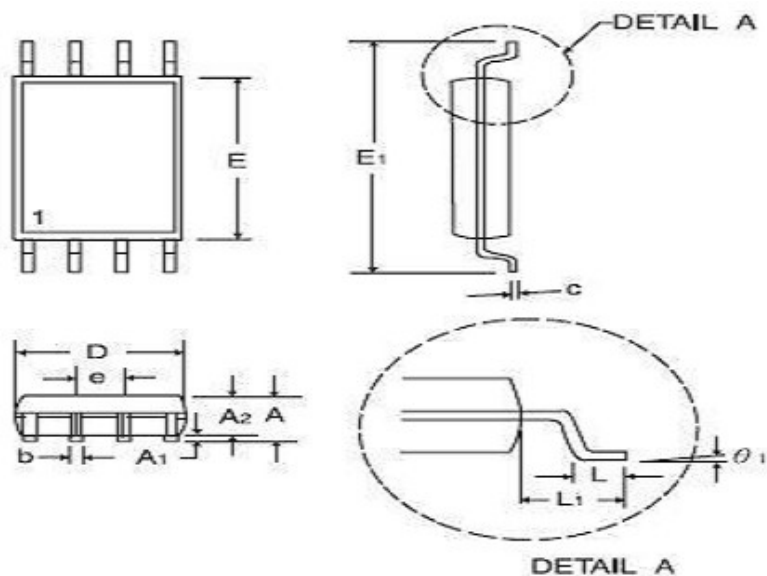


Figure 11: Normalized Maximum Transient Thermal Impedance

Package Outline Dimension

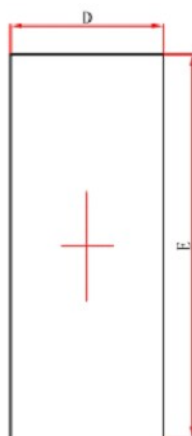
TSSOP-8



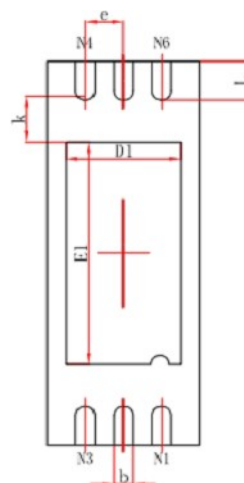
SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.05	1.20	0.041	0.047
A1	0.05	0.15	0.002	0.006
A2	-	1.05	-	0.041
b	0.20	0.28	0.008	0.011
c	0.127		0.005	
D-8	2.90	3.10	0.114	0.122
E	4.30	4.50	0.169	0.177
E1	6.20	6.60	0.244	0.260
e	0.65BSC		0.025BSC	
L	0.50	0.70	0.020	0.028
L1	1.00		0.039	
θ_1	0°	8°	0°	8°

Package Outline Dimension

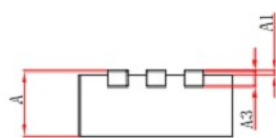
DFN5X2



Top View



Bottom View



Side View

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700/0.800	0.800/0.900	0.028/0.031	0.031/0.035
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	4.924	5.076	0.194	0.200
D1	1.400	1.600	0.055	0.063
E1	2.800	3.000	0.110	0.118
k	0.200MIN.		0.008MIN.	
b	0.200	0.300	0.008	0.012
e	0.500TYP.		0.020TYP.	
L	0.374	0.526	0.015	0.021

Package Outline Dimension

DFN3X3

